## REMARKS

Claims 8 and 10 - 16 are pending in this application, of which claims 10 - 15 have been withdrawn from consideration. By this Amendment, claim 8 has been amended, new claim 16 has been added and claims 1 and 3 - 6 have been canceled without prejudice or disclaimer. The applicant respectfully submits that no new matter has been added. It is believed that this Response is fully responsive to the Office Action dated July 3, 2002.

# In The Drawings:

In item 1 of the Office Action, the drawings are objected to since the figures are improperly cross hatched. A Request for Approval of Drawing Corrections is attached with corrected Figures 2 - 20. Applicants respectfully request approval of the corrections. Moreover, it is respectfully submitted that the cross-hatching sections of the electronic component (11) and the printed circuit board (13) have been omitted because such cross-hatching would complicate the figures.

# 35 U.S.C. §112, First And Second Paragraph, Rejection:

In item 3 of the Office Action, claim 8 stands rejected under 35 U.S.C. §112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

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**AMENDMENT** 

In item 5 of the Office Action, claim 8 stands rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Both of these rejections are respectfully traversed.

Applicant respectfully assert that the amendment to claim 8 overcomes the rejections of claim 8 under §112, first and second paragraphs. More specifically, it is respectfully submitted that the invention defined in claim 8 may also be applied to an interposer creating a constriction in a solder bump, since the claimed coating is only used to collect the melted solder bump or material of the solder bump in a facilitated manner. Although any explicit description fails to exist in the specification, the skilled person in the art should understand it based on any combination of the specified embodiments in the specification. The skilled person in the art can make and use the claimed invention specifically applied to an interposer with a through hole creating the constriction in a solder bump, based on the disclosure of the application.

Accordingly, withdrawal of the rejections of claim 8 under 35 U.S.C. §112, first and second paragraphs, is respectfully solicited.

## **AMENDMENT**

Further, Applicant gratefully acknowledges that no prior art is applied to claim 8. Thus, it is respectfully asserted that all of the remaining pending claims 8 and 16 are indicated as being allowable over the prior art of record. Therefore, it is respectfully requested that the Examiner allow these claims, along with the entire application, to issue.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Markings to Show Changes Made."

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

#### **AMENDMENT**

In the event that this paper is not timely filed, applicant respectfully petitions for an appropriate extension of time. The fees for such an extension or any other fees which may be due with respect to this paper, may be charged to Deposit Account No. 01-2340.

Respectfully submitted,

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PATENT TRADEMARK OFFICE

Enclosures: Version with markings to show changes made

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## **AMENDMENT**

# VERSION WITH MARKINGS TO SHOW CHANGES MADE Serial No. 09/536,993

# **IN THE CLAIMS:**

Claims 1 and 3 - 6 have been canceled without prejudice or disclaimer.

Claim 8 has been amended as follows:

8. (Twice Amended) The printed circuit board unit [according to claim 1,] comprising: a printed circuit board;

an electronic component;

a solder bump interposed between the printed circuit board and the electronic component so as to fix the electronic component to the printed circuit board; and,

an interposer disposed between the printed circuit board and the electronic component so as to define a through hole for containing the solder bump,

wherein at least an inner surface of the through hole is covered with a coating wet to a melted state of the solder bump.